

MRF24WB0MA/MRF24WB0MB Data Sheet

2.4 GHz, IEEE Std. 802.11bTM
RF Transceiver Module

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the
 intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not
 mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION. QUALITY, PERFORMANCE, MERCHANTABILITY FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, KEELOQ, KEELOQ logo, MPLAB, PIC, PICmicro, PICSTART, PIC³² logo, rfPIC and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

FilterLab, Hampshire, HI-TECH C, Linear Active Thermistor, MXDEV, MXLAB, SEEVAL and The Embedded Control Solutions Company are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, Application Maestro, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, dsPICworks, dsSPEAK, ECAN, ECONOMONITOR, FanSense, HI-TIDE, In-Circuit Serial Programming, ICSP, Mindi, MiWi, MPASM, MPLAB Certified logo, MPLIB, MPLINK, mTouch, Omniscient Code Generation, PICC, PICC-18, PICDEM, PICDEM.net, PICkit, PICtail, REAL ICE, rfLAB, Select Mode, Total Endurance, TSHARC, UniWinDriver, WiperLock and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

All other trademarks mentioned herein are property of their respective companies.

© 2010 - 2011, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

Printed on recycled paper.

QUALITY MANAGEMENT SYSTEM

CERTIFIED BY DNV

ISO/TS 16949:2009

ISBN: 978-1-61341-261-9

Microchip received ISO/TS-16949:2002 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.



MRF24WB0MA/MRF24WB0MB Data Sheet 2.4 GHz IEEE Std. 802.11bTM

Features:

- IEEE Std. 802.11-compliant RF Transceiver
- · Serialized unique MAC address
- · Data Rate: 1 and 2 Mbps
- IEEE Std. 802.11b/g/n compatible
- Small size: 21mm x 31mm 36-pin Surface Mount Module
- Integrated PCB antenna (MRF24WB0MA)
- External antenna option (MRF24WB0MB) with ultra miniature coaxial (U.FL) connector
- Range: up to 400m (1300 ft.)
- Easy integration into final product accelerates product development, provides quicker time to market
- Radio regulation certification for United States (FCC), Canada (IC), Europe (ETSI) and Japan (ARIB)
- Wi-Fi[®] certified (WFA ID: WFA7150)
- Designed for use with Microchip microcontroller families (PIC18, PIC24, dsPIC33, and PIC32) with downloadable Microchip TCP/IP Stack

Operational:

- Single operating voltage: 2.7V-3.6V (3.3V typical)
- Temperature Range: -20° C to +85° C extended commercial
- · Simple, four-wire SPI interface with interrupt
- Low-current consumption:
 - RX mode 85 mA (typical)
 - TX mode 154 mA (+10 dBm typical)
 - Sleep 250 µA (typical)
 - Hibernate <0.1 µA (typical)

RF/Analog Features:

- ISM Band 2.400-2.484 GHz operation
- 14 Channels selectable individually or domainrestricted
- DSSS Modulation
- Data Rate 1000 kbps
- -91 dBm Typical sensitivity at 1 Mbps
- +10 dBm Typical output power with control
- Integrated low phase noise VCO, RF frequency synthesizer, PLL loop filter and PA

- · Digital VCO and filter calibration
- Integrated RSSI ADC and I/Q DACs, RSSI readings available to host
- Balanced receiver and transmitter characteristics for low power consumption

MAC/Baseband Features:

- Hardware CSMA/CA access control, automatic ACK, and FCS creation and checking
- · Automatic MAC packet retransmit
- Hardware Security Engine for AES and RC4-based ciphers
- Supports 802.1x, 802.1i security: WEP, WPA-PSK, and WPA-2-PSK.

Applications:

- · Utility and Smart Energy
 - Thermostats
 - Smart Meters
 - White Goods
 - HVAC
- · Consumer Electronics
 - Remote Control
 - Internet Radio
 - Home Security
 - Toys
- Industrial Controls
 - Chemical Sensors
 - HVAC
 - Security Systems
 - M2M Communication
- · Remote Device Management
 - Location and Asset Tracking
 - Automotive
 - Code Update
- Retail
 - POS Terminals
 - Wireless Price Tags
 - Digital Remote
- · Medical, Fitness, and Health care
 - Glucose Meters
 - Fitness Equipment
 - Patient Asset Tracking

Pin Diagram

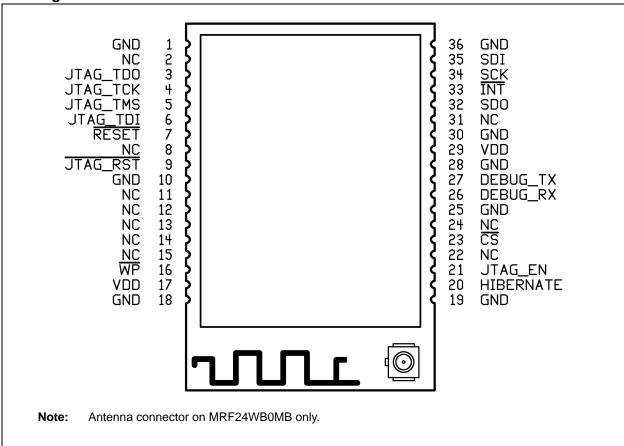


Table of Contents

1.0	Devices Overview	
2.0	Circuit Description	1
3.0	Regulatory Approval	2
4.0	Electrical Characteristics	2
	ndix A: Revision History	
The I	Microchip Web Site	3
	omer Change Notification Service	
	omer Support	
Read	er Response	3
Prod	uct Identification System	3

TO OUR VALUED CUSTOMERS

It is our intention to provide our valued customers with the best documentation possible to ensure successful use of your Microchip products. To this end, we will continue to improve our publications to better suit your needs. Our publications will be refined and enhanced as new volumes and updates are introduced.

If you have any questions or comments regarding this publication, please contact the Marketing Communications Department via E-mail at **docerrors@microchip.com** or fax the **Reader Response Form** in the back of this data sheet to (480) 792-4150. We welcome your feedback.

Most Current Data Sheet

To obtain the most up-to-date version of this data sheet, please register at our Worldwide Web site at:

http://www.microchip.com

You can determine the version of a data sheet by examining its literature number found on the bottom outside corner of any page. The last character of the literature number is the version number, (e.g., DS30000A is version A of document DS30000).

Frrata

An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

To determine if an errata sheet exists for a particular device, please check with one of the following:

- Microchip's Worldwide Web site; http://www.microchip.com
- Your local Microchip sales office (see last page)

When contacting a sales office, please specify which device, revision of silicon and data sheet (include literature number) you are using.

Customer Notification System

Register on our web site at www.microchip.com to receive the most current information on all of our products.

NOTES:

1.0 DEVICES OVERVIEW

The MRF24WB0MA and MRF24WB0MB are low-power, 2.4 GHz, IEEE Std. 802.11-compliant, surface mount modules with all associated RF components – crystal oscillator, bypass and bias passives with integrated MAC, baseband, RF and power amplifier, and built-in hardware support for AES, and TKIP (WEP, WPA, WPA2 security). The integrated module design frees the designer from RF and antenna design tasks and regulatory compliance testing, ultimately providing quicker time to market.

The MRF24WB0MA module is approved for use with the integrated PCB meander antenna.

The MRF24WB0MB comes with an ultra miniature coaxial connector (U.FL) and is approved for use with a list of pre-certified antennas. See Section 2.8, External Antenna, for specific recommendations.

The MRF24WB0MA/MRF24WB0MB modules are designed to be used with Microchip's TCP/IP software stack. The software stack has an integrated driver that implements the API that is used in the modules for command and control, and for management and data packet traffic.

The Microchip TCP/IP software stack is available in the free *Microchip Application Libraries* download (including example applications and source code) from the Microchip web site, http://www.microchip.com/wireless.

The combination of the module and a PIC running the TCP/IP stack results in support for IEEE Standard 802.11 and IP services. This allows, the immediate implementation of a wireless web server.

The MRF24WB0MA/MRF24WB0MB modules have received regulatory approvals for modular devices in the United States (FCC), Canada (IC), and Europe (ETSI). The modular approval removes the need for expensive RF and antenna design, and allows the end user to place the modules inside a finished product and not require regulatory testing for an intentional radiator (RF transmitter). They also have Radio Type Approval Certification for Japan. See Section 3.0, Regulatory Approval, for the specific requirements that should be adhered to by the integrator.

1.1 Interface Description

The block diagram in Figure 1-1 represents a MRF24WB0MA/MRF24WB0MB module. It interfaces to Microchip PIC18, PIC24, dsPIC33, or PIC32 microcontrollers through a four-wire serial slave SPI interface – interrupt, hibernate, reset, power and ground signals. The module runs on a single supply voltage of nominally 3.3V. It also supports optional JTAG and serial debug for testability. The debug port operates at 3.3V and requires a level shifter for operation with RS-232 devices. Figure 1-2 shows a simplified example connection between a Microchip PIC MCU and the module. Table 1-1 lists the pin descriptions.

Data communications with the MRF24WB0MA/ MRF24WB0MB are through the SPI interface that is detailed in Section 2.0, Circuit Description. The Microchip PIC microcontroller communicates with the module through a command API from within the Microchip TCP/IP stack. The command API is detailed in the Microchip TCP/IP stack online help that is included in the free *Microchip Application Libraries* download.

FIGURE 1-1: MRF24WB0MA/MRF24WB0MB BLOCK DIAGRAM

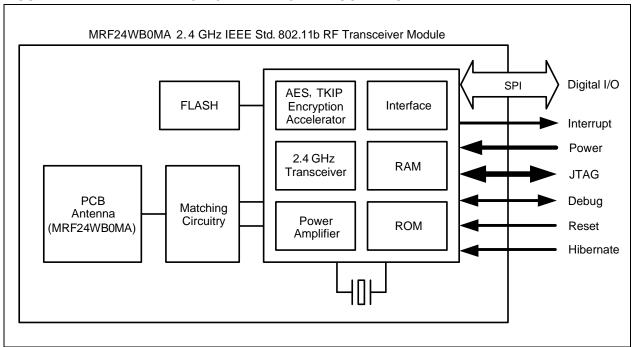


FIGURE 1-2: MICROCONTROLLER TO MRF24WB0MA/MRF24WB0MB INTERFACE

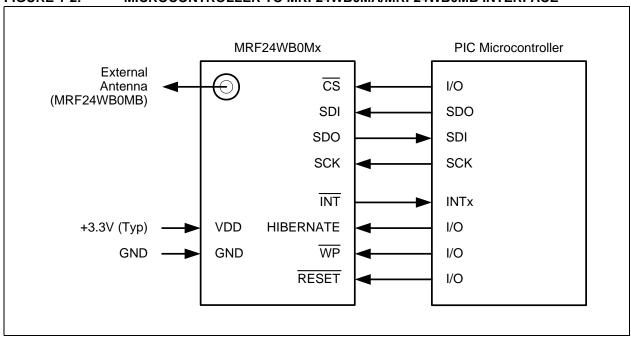


TABLE 1-1: Pin Description

Pin	Symbol	Туре	Description
1	GND	Р	Ground
2	NC	NC	Do not connect
3	JTAGTDO	0	JTAG test data output
4	JTAGTCK	I: Constant ⁽¹⁾	JTAG clock input
5	JTAGтмs	I	JTAG mode input
6	JTAGTDI	I	JTAG test data input
7	RESET	I: Constant ⁽¹⁾	Module Reset input
8	NC	NC	Do not connect
9	JTAGRST	I	JTAG Reset input (optional; see Section 2.0, Circuit Description)
10	GND	Р	Ground
11	NC	NC	Do not connect
12	NC	NC	Do not connect
13	NC	NC	Do not connect
14	NC	NC	Do not connect
15	NC	NC	Do not connect
16	WP ⁽²⁾	I	Write protect (this pin is used to enable FLASH update)
17	Vdd	Р	Power
18	GND	Р	Ground
19	GND	Р	Ground
20	HIBERNATE	I	Hibernate mode enable (high input will disable the module)
21	JTAGEN	1	JTAG test enable
22	NC	NC	Do not connect
23	CS	I: Constant ⁽¹⁾	SPI Chip Select input, constant drive or pull-up required
24	NC	NC	Do not connect
25	GND	Р	Ground
26	DEBUGRX	I	Serial debug port input (see Section 2.0, Circuit Description)
27	DEBUGTX	0	Serial debug port output (see Section 2.0, Circuit Description)
28	GND	Р	Ground
29	Vdd	Р	Power
30	GND	Р	Ground
31	NC	NC	Do not connect
32	SDO	0	SPI data out
33	ĪNT	0	Interrupt output (open drain – requires a pull-up)
34	SCK	I	SPI clock input
35	SDI	I	SPI data in
36	GND	Р	Ground

Legend: Pin type abbreviation: P = Power input, I = Input, O = Output, NC = Do Not Connect

2: WP is used as write-protect for the internal module SPI Flash. For production use, this pin should be pulled low. This pin can be controlled by the host microcontroller to enable in field Flash updates.

Note 1: Signals of Type "I: Constant" must either be constantly driven by the host or have a pull-up or pull-down (in case the host is likely to tri-state the signal during power down modes). The constant drive is used to ensure defined operation of the part and to minimize leakage current during low power modes.

1.2 Mounting Details

The MRF24WB0MA/MRF24WB0MB is a surface mountable module. Module dimensions are shown in Figure 1-3. The module Printed Circuit Board (PCB) is 1 mm thick with castellated mounting points on two sides.

FIGURE 1-3: MRF24WB0MA/MRF24WB0MB MODULE PHYSICAL DIMENSIONS

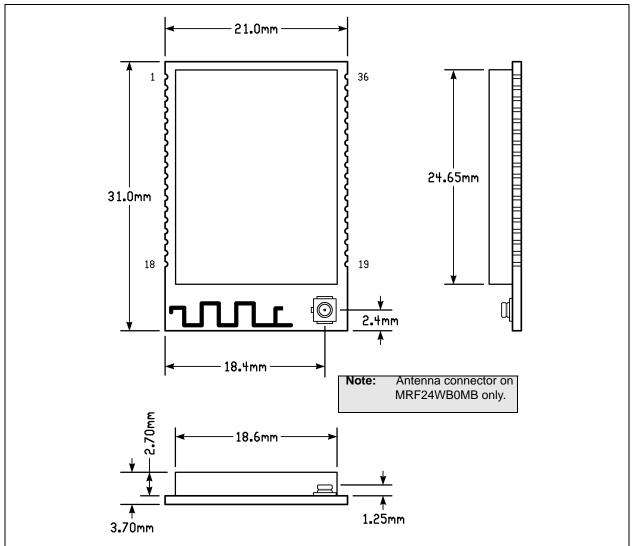
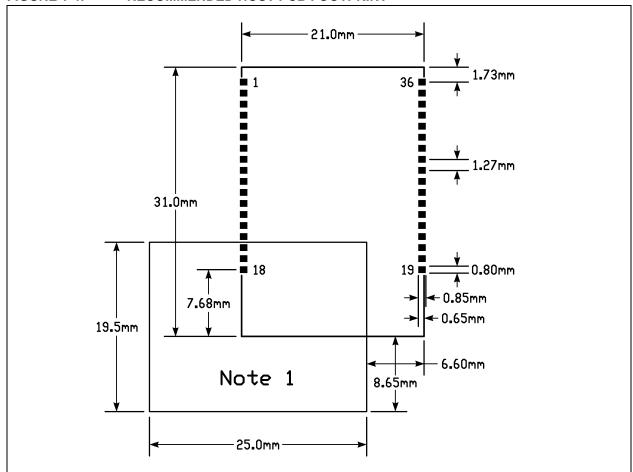


Figure 1-4 shows the recommended host PCB footprint for the module.

The MRF24WB0MA has an integrated PCB antenna. For best performance, follow the mounting details shown in Figure 1-4.

For best performance, mount the module on the PCB without metal obstructions in the keep out area of Figure 1-4. The antenna is tuned to have FR4 PCB material underneath the module. Do not "cut-out" host PCB material under the antenna.

FIGURE 1-4: RECOMMENDED HOST PCB FOOTPRINT



Note 1: The "Note 1" demarcation specifies the host PCB copper plane keep-out area on underlying board layers. It is alright to route surface escape traces in this area.

Figure 1-5 illustrates the module reflow profile that is recommended for mounting the device onto the host PCB.

FIGURE 1-5: RECOMMENDED MODULE REFLOW PROFILE AND SETPOINTS

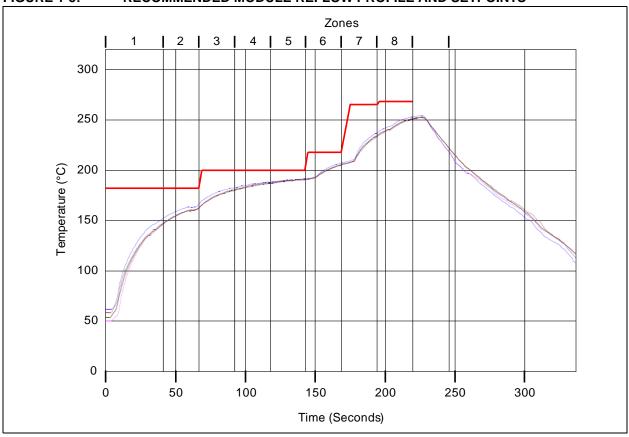


TABLE 1-2: MODULE REFLOW PROFILE⁽¹⁾

Zone	1	2	3	4	5	6	7	8
Temperature (°C)	180°	180°	200°	200°	200°	220°	265°	270°

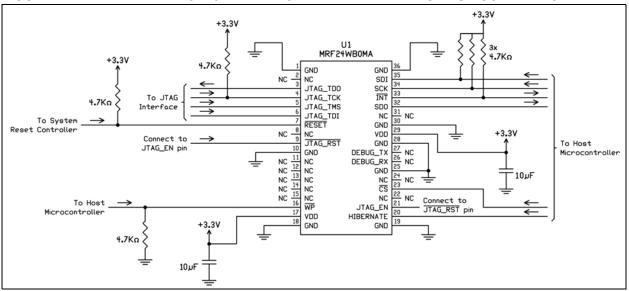
Note 1: Conveyor Speed: 90 cm/min

2.0 CIRCUIT DESCRIPTION

The MRF24WB0MA/MRF24WB0MB interfaces to Microchip PIC18, PIC24, dsPIC33, and PIC32 microprocessors with a minimal of external components through digital-only connections. This section details use of the module, starting with an example host connection as shown in Figure 2-1.

2.1 Schematic

FIGURE 2-1: MRF24WB0MA/MRF24WB0MB EXAMPLE APPLICATION SCHEMATIC

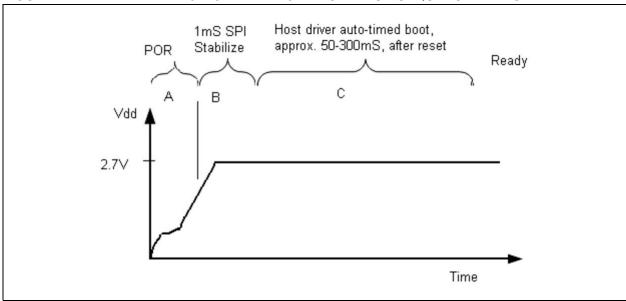


2.2 Power-On Sequence

The internal regulators for the digital and analog core power supplies are disabled by driving the HIBERNATE pin high. Figure 2-2 shows the power up sequence for the MRF24WB0MA/MRF24WB0MB.

There is an internal Power-on-Reset (POR) circuit which keeps the module in reset until VDD is within specification. The Hibernate and Reset signals are also used to control startup. In Figure 2-2, section A is controlled by the internal POR and section B is an allowance for the SPI bus to stabilize when the module supplies are enabled. Once Hibernate is disabled, the host software provides 1mS of startup to allow the SPI to stabilize. This time is pre-programmed into the host driver, and may need to be increased if insufficient initial drive current is not provided to the MRF24WB0M module. Section C is the driver controlled release from Reset period. This takes approximately 300 mS and is monitored by the stack driver. No additional time needs to be provided by user software for startup.

FIGURE 2-2: MRF24WB0MA/MRF24WB0MB POWER-ON SEQUENCE TIMING



2.3 Power States

The MRF24WB0MA/MRF24WB0MB has several power states. These are Hibernate, Sleep and Active (two sub-states), as shown in Figure 2-3. The selection of power state directly affects system behavior, and overall power consumption or battery life. There is also a "Standby" state that is not user-controlled.

2.3.1 HIBERNATE STATE

An "Off" state is defined as no power applied to the device. The Hibernate mode is the closest to controlled off that the module can approach. It is controlled through the HIBERNATE pin (high input puts the module into Hibernate). When in Hibernate, the module only consumes leakage current, but does not maintain state. Hibernate has to be fully controlled by the PIC MCU and requires the TCP/IP stack to restart on an awake.

The module contains about $70\mu F$ of internal bulk capacitance. Supplies should be provisioned to supply sufficient charge on release of hibernate for desired start time or sufficient delay must be provided in software after hibernate release and before releasing reset.

This state provides the best battery life for embedded products. Entering Hibernate for intervals of less than 30 seconds is not likely to save power. Battery life expectation can be more than a year for devices operating on AA cells that would be in Hibernate except to wake up every hour for a small data transfer (<500 Bytes).

2.3.2 SLEEP STATE

The Sleep state is a low power dynamic state that automatically implements the 802.11 Power Save feature. In this mode, if enabled, the module will enter Power Save mode when all activity is complete.

The module will wake autonomously to any PIC intervention so it can check DTIM beacons from the Access Point. If any traffic is listed as queued for the module, then it will awaken and get the data from the Access Point on the next possible opportunity. When data is acquired, the module will interrupt the PIC microcontroller on a normal "data available" indication. If no data is available on a DTIM check, the module reenters the Power Save state until the next DTIM. The DTIM interval is programmed at the Access Point. This state can provide "as if on" behavior of the radio with a significant power savings versus "always on". The battery life expectation of this mode is several days to several weeks. This mode is characterized by a very low latency (as low as 200 mS) to begin data transfer from the low power state.

2.3.3 ACTIVE STATE

The Active state is identified as one of two states where the radio circuitry is fully on. The two active states are the Receive state (RX ON) and the Transmit state (TX ON).

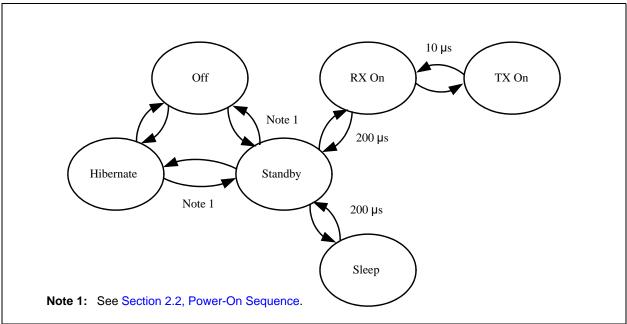
2.3.4 STANDBY STATE

The Standby state is not user-controlled but is noted as it helps identify and track certain operations of the module during power tracing.

TABLE 2-1: MRF24WB0MA/MRF24WB0MB POWER STATE DEFINITIONS

State	VDD	cs	Description
Off	0V	0V	Power is completely disconnected
Hibernate	3.3V	3.3V	All internal power regulators are OFF – enabled by HIBERNATE pin
Sleep	3.3V	0V	Enabled by TCP/IP driver
RX ON	3.3V	0V	Receive circuits are on and receiving
TX ON	3.3V	0V	Transmit circuits are on and transmitting
Standby	3.3V	0V	State machine transition state only – not user controlled

FIGURE 2-3: MRF24WB0MA/MRF24WB0MB POWER-STATE DIAGRAM



2.4 JTAG Interface

Joint Test Action Group (JTAG) is the common name used for the IEEE 1149.1 standard entitled *Standard Test Access Port and Boundary-Scan Architecture* for test access ports that are used for testing printed circuit boards using boundary scan. The MRF24WB0MA/MRF24WB0MB supports JTAG boundary scan. The JTAG port provides the optional hardware JTAG Reset input, JTAGRST. JTAG_EN and JTAGRST need to be driven high to enable JTAG mode. JTAG should not be enabled during normal functional operation. This function affects power state current.

2.5 Debug Serial Interface

The MRF24WB0MA/MRF24WB0MB incorporates a Transmit Data pin (DEBUGTx) and a Receive Data pin (DEBUGRx) for serial debugging purposes. These pins can be connected to commercially available RS-232 line drivers/receivers with appropriate external level shifters. The serial interface operates at 19200, 8, N, 1, N.

2.6 SPI Interface

The slave Serial Peripheral Interface (SPI) is used to interface with the host PIC microcontroller. The slave SPI interface works with the Interrupt line (INT). When data is available for the PIC microcontroller during operation, the INT line is asserted (logic low) by the MRF24WB0MA/MRF24WB0MB module. The INT line is de-asserted (logic high) by the MRF24WB0MA/MRF24WB0MB after the data is transferred to the host PIC microcontroller. The SPI SCK frequency can be up to 25 MHz.

The slave SPI interface implements the [CPOL=0; CPHA=0] and [CPOL=1; CPHA=1] modes (0 and 3) of operation. That is, data is clocked in on the first rising edge of the clock after Chip Select (CS) is asserted.

Data is placed on the bus with most significant bit (MSb) first.

The $\overline{\text{CS}}$ pin must be toggled with transfer blocks and cannot be held low permanently. The falling edge of $\overline{\text{CS}}$ is used to indicate the start of a transfer. The rising edge of $\overline{\text{CS}}$ is used to indicate the completion of a transfer.

Figure 4-1 in Section 4.0, Electrical Characteristics shows the SPI timing diagram. Table 4-7 details the SPI timing AC characteristics.

2.7 PCB Antenna

For the MRF24WB0MA, the PCB antenna is fabricated on the top copper layer and covered in solder mask. The layers below the antenna have no copper trace.

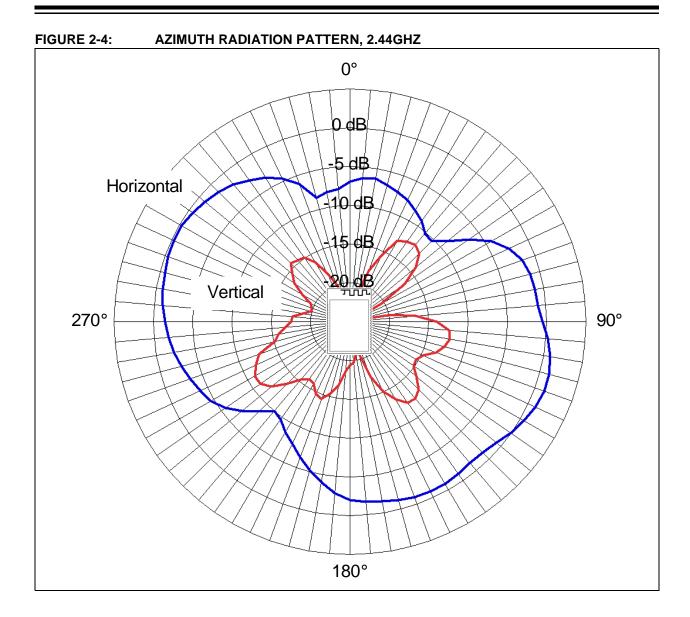
It is recommended that the module be mounted on the edge of the host PCB. It is permitted for PCB material to be below the antenna structure of the module as long as no copper traces or planes are on the host PCB in that area. For best performance, place the module on the host PCB according to the details shown in Figure 1-4.

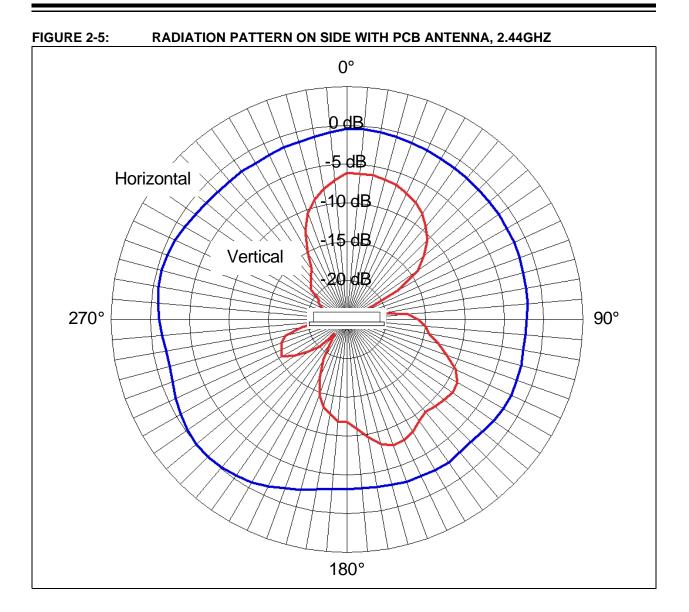
The antenna patterns shown in the following plots, designated as Figure 2-4, Figure 2-5 and Figure 2-6, refer to three separate axis of measurement that correspond to the orientation of the module (drawn in the center of each plot).

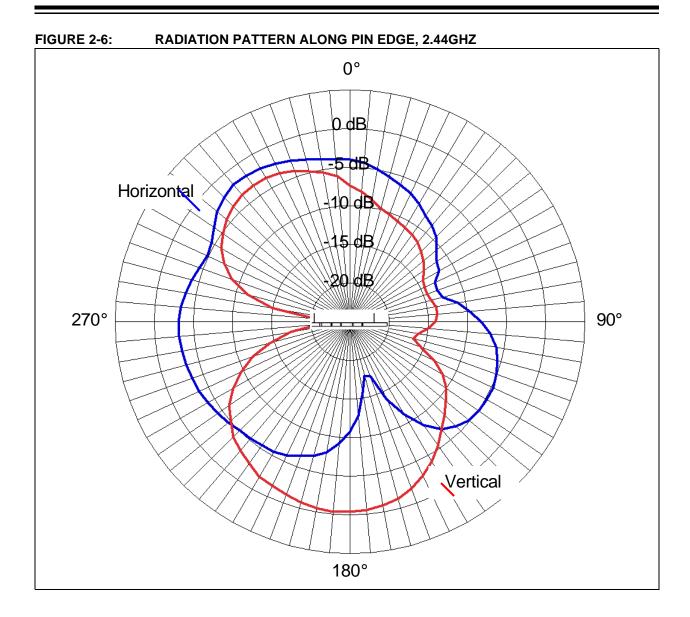
The horizontal and vertical data, blue and red respectively, in each plot correspond to the orientation (polarization) of the measurement antenna rotated 360 degrees around the module.

The horizontal measurement was done with the receive antenna parallel with the module PCB. The vertical measurement was done perpendicular to the module PCB.

These patterns allow the designer to understand the performance of the module with respect to the position of the receive/transmit antenna at the other end of the link. Figure 2-4, Figure 2-5 and Figure 2-6 show the simulated radiation patterns expected from the PCB antenna.







2.8 External Antenna

The MRF24WB0MB has been regulatory certified for use with a number of antennas. The modular certifications hold only if the following antennas, or antennas that are materially and functionally equivalent, are used. All antennas connect to the module through an ultra miniature coaxial (U.FL or IPEX) connector.

A list of antennas for use with the module is provided in Table 2-2.

TABLE 2-2: LIST OF CERTIFIED EXTERNAL ANTENNAS

Part Number	Туре	Gain (dBi)	VSWR Max.	Connector	Vendor
RFA-02-P05	PCB	2	2.0	IPEX	Aristotle
RFA-02-L6H1-70-35	Dipole	2	2.0	IPEX	Aristotle
RFA-02-D3	Dipole	1.5	2.0	IPEX	Aristotle
RFA-02-L2H1	Dipole	2	2.0	IPEX	Aristotle
RFA-02-3-C5H1	Dipole	3	2.0	IPEX	Aristotle
RFA-02-5-C7H1	Dipole	5	2.0	IPEX	Aristotle
RFA-02-5-F7H1	Dipole	5	2.0	IPEX	Aristotle
WF2400-15001A	Dipole	5	2.0	IPEX	Saytec
WF2400-15001AR	Dipole	5	2.0	RF-IPEX	Saytec
WF2400-10001I	Dipole	2	2.0	IPEX	Saytec
WF2400-10001R	Dipole	2	2.0	RF-IPEX	Saytec
AN2400-5901RS, used with connector SMASFR8-3152H-00X00I	Omni	9	2.0	IPEX	Saytec
AN2400-5901RS, used with connector SMASFR8-3152H-00X00IR	Omni	9	2.0	RF-IPEX	Saytec

NOTES:

3.0 REGULATORY APPROVAL

The MRF24WB0MA/MRF24WB0MB module has received regulatory approvals for modular devices in the United States, Canada and European countries. Modular approval allows the end user to place the MRF24WB0MA/MRF24WB0MB module inside a finished product and not require regulatory testing for an intentional radiator (RF transmitter), provided no changes or modifications are made to the module circuitry. Changes or modifications could void the user's authority to operate the equipment. The end user must comply with all of the instructions provided by the Grantee, which indicate installation and/or operating conditions necessary for compliance.

The integrator may still be responsible for testing the end product for any additional compliance requirements that become necessary with this module installed (for example, digital device emission, PC peripheral requirements, etc.) in the specific country that the end device will be marketed.

Refer to the specific country radio regulations for details on regulatory compliance.

3.1 United States

The MRF24WB0MA/MRF24WB0MB has received Federal Communications Commission (FCC) CFR47 Telecommunications, Part 15 Subpart C "Intentional Radiators" 15.247 and modular approval in accordance with FCC Public Notice DA 00-1407 Released: June 26, 2000, Part 15 Unlicensed Modular Transmitter Approval. The MRF24WB0MA/MRF24WB0MB module can be integrated into a finished product without obtaining subsequent and separate FCC approvals for intentional radiation.

The MRF24WB0MA/MRF24WB0MB module has been labeled with its own FCC ID number, and if the FCC ID is not visible when the module is installed inside another device, then the outside of the finished product into which the module is installed must also display a label referring to the enclosed module. The following examples present terminology that could be used:

Contains Transmitter Module FCC ID: W7OZG2100-ZG2101

or

Contains FCC ID: W7OZG2100-ZG2101

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

(1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

A user's manual for the product should include the following statement:

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy, and if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- · Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.1.1 RF EXPOSURE

All transmitters regulated by FCC must comply with RF exposure requirements. OET Bulletin 65, *Evaluating Compliance with FCC Guidelines for Human Exposure to Radio Frequency Electromagnetic Fields*, provides assistance in determining whether proposed or existing transmitting facilities, operations or devices comply with limits for human exposure to Radio Frequency (RF) fields adopted by the Federal Communications Commission (FCC). The bulletin offers guidelines and suggestions for evaluating compliance.

If appropriate, compliance with exposure guidelines for mobile and unlicensed devices can be accomplished by the use of warning labels and by providing users with information concerning minimum separation distances from transmitting structures and proper installation of antennas.

The following statement must be included as a CAUTION statement in manuals and OEM products to alert users of FCC RF exposure compliance:

To satisfy FCC RF Exposure requirements for mobile and base station transmission devices, a separation distance of 20 cm or more should be maintained between the antenna of this device and persons during operation. To ensure compliance, operation at closer than this distance is not recommended.

The antenna(s) used for this transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

If the MRF24WB0MA/MRF24WB0MB module is used in a portable application (i.e., the antenna is less than 20 cm from persons during operation), the integrator is responsible for performing Specific Absorption Rate (SAR) testing in accordance with FCC rules 2.1091.

3.1.2 HELPFUL WEB SITES

Federal Communications Commission (FCC): http://www.fcc.gov.

3.2 Canada

The MRF24WB0MA/MRF24WB0MB module has been certified for use in Canada under Industry Canada (IC) Radio Standards Specification (RSS) "RSS-210" and "RSS-Gen".

From "Section 7.1.1, RSS-Gen", Issue 2, June 2007, *Modular Transmitter Approval*:

"Host devices which contain separately certified modules do not need to be recertified, provided that they meet the following conditions:

- a)The host device, as a stand-alone unit without any separately certified modules, complies with all applicable Radio Standards Specifications.
- b)The host device and all the separately certified modules it contains jointly meet the RF exposure compliance requirements of "RSS-102", if applicable.
- c)The host device complies with the certification labeling requirements of each of the modules it contains."

The following example demonstrates labeling compliance.

NOTE: Compliance of a module in its final configuration is the responsibility of the applicant. A host device will not be considered certified if the instructions regarding antenna configuration provided in the original description, of one or more separately certified modules it contains, were not followed.

From "Section 5.2, RSS-Gen", Issue 2, June 2007, *Equipment Labels*:

"All Category I radio equipment intended for use in Canada shall permanently display on each transmitter, receiver or inseparable combination thereof, the applicant's name (i.e., manufacturer's name, trade name or brand name), model number and certification number. This information shall be affixed in such a manner as to not be removable except by destruction or defacement. The size of the lettering shall be legible without the aid of magnification, but is not required to be larger than 8-point font size. If the device is too small to meet this condition, the information can be included in the user manual upon agreement with Industry Canada."

The label is shown in the following example:

Contains IC: 8248A-G21ZEROG

From "Section 7.1.6, RSS-Gen", Issue 2, June 2007, Digital Circuits:

"If the device contains digital circuitry that is not directly associated with the radio transmitter, the device shall also have to comply with ICES-003, Class A or B as appropriate, except for ICES-003 labeling requirements. The test data obtained (for the ICES-003 tests) shall be kept by the manufacturer or importer whose name appears on the equipment label, and made available to Industry Canada on request, for as long as the model is being marketed in Canada."

3.2.1 HELPFUL WEB SITES:

Industry Canada: http://www.ic.gc.ca/

3.3 Europe

The MRF24WB0MA/MRF24WB0MB module has been certified for use in European countries. The following testing has been completed:

Test standard ETSI EN 300 328 V1.7.1 (2006-10):

- · Maximum Transmit Power
- Maximum EIRP Spectral Density
- · Frequency Range
- Radiated Emissions

Test standards ETSI EN 301 489-1:2008 and ETSI EN 301 489-17:2008:

- Radiated Emissions
- · Electro-Static Discharge
- Radiated RF Susceptibility

The modules are fully compliant with

- Radiated Emissions EN 55022
- Electrostatic Discharge EN 61000-4-2
- Radiated Immunity EN 61000-4-3
- EN 60950-1
- CE-Mark
- RoHS

ETSI does not provide a modular approval similar to the USA (FCC) and Canada (IC). However, the testing completed above can be used as part of the customer's application for certification. The test report data can be included in their test plan and can significantly the lower customer's certification burden.

A helpful document that can be used as a starting point in understanding the use of Short Range Devices (SRD) in Europe is the European Radio Communications Committee (ERC) Recommendation "70-03 E", downloadable from the European Radio Communications Office (ERO): http://www.ero.dk/

The end user is responsible for ensuring compliance with harmonized frequencies and labeling requirements for each country in which the end device is marketed and sold.

3.3.1 HELPFUL WEB SITES:

Radio and Telecommunications Terminal Equipment (R&TTE):

http://ec.europa.eu/enterprise/rtte/index_en.htm

European Conference of Postal and Telecommunications Administrations (CEPT):

http://www.cept.org/

European Telecommunications Standards Institute (ETSI):

http://www.etsi.org/

European Radio Communications Office (ERO): http://www.ero.dk/

3.4

Should other regulatory jurisdiction certification be required by the customer, or the customer need to recertify the module for other reasons, a certification utility is available. The utility runs on a Window's PC and utilizes a USB to SPI converter to interface to the MRF24WB0M module. In order to use the utility, the MRF24WB0M module must be out of reset and not accessed by the system host. That is, the SPI signals to the MRF24WB0M must be tri-state, with Reset and Hibernate deasserted. The following signals will need to be brought from the MRF24WB0M for connection to the PC (through the USB adapter):

- SDO
- SDI
- <u>CS</u>
- SCK
- INT
- GND

For further regulatory Certification Utility and documentation, contact your local Microchip salesperson.

3.5 Wi-Fi[®] Alliance

Wi-Fi Alliance Certification focuses on interoperability testing of devices based on 802.11 standards.

Historically, when the certification process and programs were developed by Wi-Fi Alliance members, the vast majority of the 802.11 clients were PC-centric, and certification testing adequately addressed those types of devices. In subsequent years, the number of Wi-Fi devices that are not PC-centric has grown significantly.

These non-standard devices, as a class of products, have been dubbed Application Specific Devices (ASDs) by the Wi-Fi Alliance. ASDs are 802.11 devices, for example clients or access points (APs), which cannot be tested under a standard Alliance test plan because they do not comply with the standard test configuration and/or because they are designed to perform a specific application. Examples include, but are not limited to: bar code scanners, pagers, recording devices, monitoring equipment, and cable modems.

The APs or clients that are used to validate ASD compliance (from the standard test bed) will meet all of the requirements specified in the applicable System Interoperability Test Plans (referred to as the "standard test plan"), unless specifically exempted. The MRF24WB0MA and MRF24WB0MB modules are in the ASD category.

The modules are certified under Wi-Fi 802.11 with WPA2, WPA, and WEP System Interoperability ASD Model Test Plan with Test Engine For IEEE 802.11a, b, and g Devices (Version 1.0).

Per the Wi-Fi Alliance approved ASD test plan, the definition of the Microchip MRF24WB0MA and MRF24WB0MB modular solutions is expressed in the following statements:

"Member Wireless solution is a single-chip 802.11b module including MAC, baseband, RF and power amplifier personal STA. It utilizes a simple to use API for embedded markets, and an OS is not a requirement for operation. It supports 1 and 2 Mbps (TX and RX). It also supports WEP, WPA Personal, and WPA2 Personal security. Ciphers supported are AES and TKIP. The Member Wireless solution interfaces with the HOST through SPI Bus. Some applications for the Member Wireless solution are as following:

- Sensors/Controls such as Industrial & Factory sensors, HVAC, & Lighting
- Consumer Electronic such as remote controls, toys, and internet radio

This certification ensures that the MRF24WB0MA and MRF24WB0MB modules have passed rigorous testing for interoperability across existing consumer and business Wi-Fi equipments, and their certifications are completed (WFA ID: WFA7150). The certification effort undertaken will save customers time and money. For modular policy, refer to WFA Module Policy (Version 2.2; MARCH 2006)."

4.0 ELECTRICAL CHARACTERISTICS

TABLE 4-1: DIGITAL ELECTRICAL CHARACTERISTICS (NOMINAL CONDITIONS: 25C, VDD = 3.3V)

Parameters	Min	Тур	Max	Units
VIL (Input low voltage)	-0.3	_	0.8	V
VIH (Input high voltage)	2	_	5.5	V
Vol (Output low voltage)	_	_	0.4	V
VOH (Output high voltage)	2.4	_	_	V
IOL (Output low level current at VoL Max)	_	8.5	_	mA
Іон (Output high level current at Voн Min)	_	15.4	_	mA

TABLE 4-2: ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Parameters	Min	Max	Notes
Storage Temperature	-40C	+125C	_
VDD	0V	4.2V for 0.5mSec	VDD above this level and duration will disable Radio
VIN on SDI, CS, SCK	-0.3V	5.5V	_

Note 1: Listed Absolute Maximum Ratings are not meant for functional operation. Operation at these levels is not guaranteed, and may reduce the operating life of the component.

TABLE 4-3: RECOMMENDED OPERATING CONDITIONS

Parameters	Min	Тур	Max	Units
Ambient Temperature ⁽²⁾	-20	_	+85	Degrees Celsius
VDD – for FCC and IC	2.70	3.3	3.63 ⁽¹⁾	Volts

Note 1: While 3.63V is the maximum operating voltage, the module will detect an overvoltage condition at 4.2V and disable the RF Transmit function after 0.5 ms. This is an RF certification requirement pertaining to disabling transmission in unforeseen overvoltage conditions.

2: Ambient temperature for industrial part number is minimum -40C to maximum +85C. Contact Microchip Sales for industrial temperature parts.

TABLE 4-4: CURRENT CONSUMPTION⁽³⁾ (NOMINAL CONDITIONS: 25C, VDD = 3.3V)

Parameters	Min	Тур	Max	Units
IDD, Hibernate = 3.3V	_	0.1	_	μA
IDD, Sleep (software enabled)	_	250 ⁽¹⁾	_	μA
IDD, Standby (transitional state)	_	10	_	mA
IDD core ⁽²⁾ , RX on, Receive @-83dBm with 2Mbps modulated signal at antenna port	_	85	_	mA
IDD core, TX on, +0 dBm	_	115	_	mA
IDD core, TX on, +10 dBm	_	154	_	mA

- Note 1: Sleep current is current consumed during periods of "standby" between DTIM beacons. The module will awake 2 mS before a DTIM and turn on its receiver, and possibly its transmitter (if data is available for it).
 - 2: IDD core is current consumed by the part not including the I/O consumption of the SPI port.
 - 3: Current Consumption values represent Typical Peak currents, and the measured current conditions were done with 85% duty cycle modulated signal. Wi-Fi applications typically operate at less than 85% TX duty cycle. TX current is dependent on such criteria as transmit power setting, and transmit data rate and bandwidth being used. RX current is affected by connection distance.

TABLE 4-5: RECEIVER AC CHARACTERISTICS⁽¹⁾

Parameters	Min	Тур	Max	Units
Flo	2412	_	2484	MHz
RX Min Input Level Sensitivity, 1Mbps, 8% PER	_	-91	_	dBm
RX Min Input Level Sensitivity, 2Mbps, 8% PER	_	-88	_	dBm
RX Max Input Level (Power), 1Mbps, 8% PER	_	-4	_	dBm
RX Max Input Level (Power), 2Mbps, 8% PER	_	-4	_	dBm

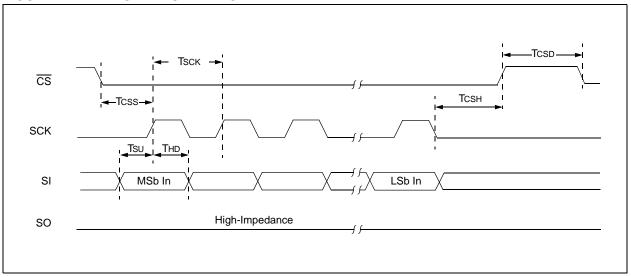
Note 1: Nominal conditions: 25C, VDD = 3.3V, Flo = 2437 MHz, measurements at antenna port.

TABLE 4-6: TRANSMITTER AC CHARACTERISTICS⁽¹⁾

Parameters	Min	Тур	Max	Units
Flo	2412	_	2484	MHz
Average Pout (transmit spectrum mask compliant)	_	+10	_	dBm
Average Pout gain step resolution from +5 to +10dBm	_	0.5	_	dB
Average Pout gain step resolution from -5 to +5dbm	_	1.0	_	dB
Average Pout settled variation	-0.5	_	0.5	dB

Note 1: Nominal conditions: 25C, VDD = 3.3V, Flo = 2437 MHz, 2 Mbps. modulated signal measured at antenna port.

FIGURE 4-1: SPI INPUT TIMING



 $\overline{\text{CS}}$ must be toggled for each SPI block transfer.

FIGURE 4-2: SPI OUTPUT TIMING

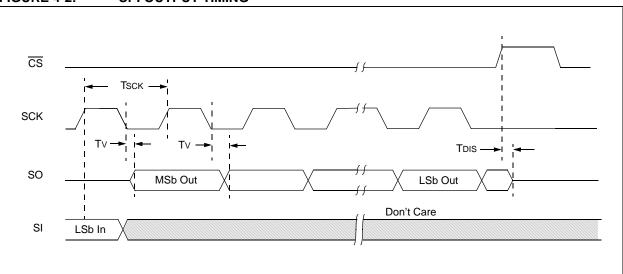


TABLE 4-7: SPI INTERFACE AC CHARACTERISTICS

Symbol	Parameters	Min	Max	Units
Tsck	SCK Period	40	_	nS
TCSD	CS High time	50	_	nS
Tcss	CS Setup time	50	_	nS
Тсѕн	CS Hold time	50	_	nS
Tsu	SDI Setup time	10	_	nS
THD	SDI Hold time	10	_	nS
Tv	SDO Valid time	_	15	nS

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (April 2010)

This is the initial release of the document.

Revision B (June 2011)

This revision includes the following updates:

- Updated Section, Operational: Changed temperature range to -20° C to +85° C
- Updated Table 1-1: Added type and pin description to pin 23.
- Updated Table 4-3
- Replaced Figure 2-2
- Updated Section 2.0, Circuit Description
- Added Section 3.4,
- Updated the temperature on the order code in Section, Product Identification System
- Minor changes to the text and formatting were incorporated throughout the document.

NOTES:

THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- Product Support Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- General Technical Support Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- Business of Microchip Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com. Under "Support", click on "Customer Change Notification" and follow the registration instructions.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- · Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support
- Development Systems Information Line

Customers should contact their distributor, representative or field application engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: http://microchip.com/support

READER RESPONSE

It is our intention to provide you with the best documentation possible to ensure successful use of your Microchip product. If you wish to provide your comments on organization, clarity, subject matter, and ways in which our documentation can better serve you, please FAX your comments to the Technical Publications Manager at (480) 792-4150.

Please list the following information, and use this outline to provide us with your comments about this document.

TO: RE:	Technical Publications Manager Reader Response	Total Pages Sent
From	Name	
	Company	
	Address	
	City / State / ZIP / Country	
	Telephone: ()	FAX: (
Applio	cation (optional):	
Would	d you like a reply?YN	
Devic	e: MRF24WB0MA/MRF24WB0MB	Literature Number: DS39957C
Ques	tions:	
1. W	/hat are the best features of this document?	
_		
2. H	ow does this document meet your hardware and softwa	are development needs?
_		
2 D	to you find the organization of this document easy to fall	low? If not, why?
3. D	o you find the organization of this document easy to fol	ow? II not, why?
4. V	hat additions to the document do you think would enha	nce the structure and subject?
_		
5 W	/hat deletions from the document could be made withou	it affecting the overall usefulness?
J. V	what deletions from the document could be made without	a directing the overall decidiness:
_		
6. Is	there any incorrect or misleading information (what an	d where)?
_		
7. H	low would you improve this document?	
_		_

PRODUCT IDENTIFICATION SYSTEM

To order parts, including industrial, or obtain information, for e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	<u>M</u>	X	Ŧ	<u>-X</u>	Examp	les:
Device	Module	Module Type	Tape and Reel	Temperature Range	b) MF	RF24WB0MA/RM = Extended commercial np. tray RF24WB0MB/RM = Extended commercial
evice		MA/MRF24WB0I ge 2.7V to 3.6V	MB;		ten	np. tray
emperature Range	-	-20°C to +85°	C (Extended	l commercial)		
	-	-40°C to +85°	C (Industrial	Temp)		
					-	

NOTES:



Worldwide Sales and Service

AMERICAS

Corporate Office

2355 West Chandler Blvd. Chandler, AZ 85224-6199

Tel: 480-792-7200 Fax: 480-792-7277 Technical Support:

http://www.microchip.com/

support

Web Address: www.microchip.com

Atlanta

Duluth, GA Tel: 678-957-9614 Fax: 678-957-1455

Boston

Westborough, MA Tel: 774-760-0087 Fax: 774-760-0088

Chicago

Itasca, IL Tel: 630-285-0071 Fax: 630-285-0075

Cleveland

Independence, OH Tel: 216-447-0464 Fax: 216-447-0643

Dallas

Addison, TX Tel: 972-818-7423 Fax: 972-818-2924

Detroit

Farmington Hills, MI Tel: 248-538-2250 Fax: 248-538-2260

Indianapolis

Noblesville, IN Tel: 317-773-8323 Fax: 317-773-5453

Los Angeles

Mission Viejo, CA Tel: 949-462-9523 Fax: 949-462-9608

Santa Clara

Santa Clara, CA Tel: 408-961-6444 Fax: 408-961-6445

Toronto

Mississauga, Ontario,

Canada

Tel: 905-673-0699 Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office

Suites 3707-14, 37th Floor Tower 6, The Gateway Harbour City, Kowloon Hong Kong

Tel: 852-2401-1200 Fax: 852-2401-3431

Australia - Sydney

Tel: 61-2-9868-6733 Fax: 61-2-9868-6755

China - Beijing

Tel: 86-10-8569-7000 Fax: 86-10-8528-2104

China - Chengdu

Tel: 86-28-8665-5511 Fax: 86-28-8665-7889

China - Chongqing

Tel: 86-23-8980-9588 Fax: 86-23-8980-9500

China - Hangzhou

Tel: 86-571-2819-3180 Fax: 86-571-2819-3189

China - Hong Kong SAR

Tel: 852-2401-1200 Fax: 852-2401-3431

China - Nanjing Tel: 86-25-8473-2460

Fax: 86-25-8473-2460

China - Qingdao

Tel: 86-532-8502-7355 Fax: 86-532-8502-7205

China - Shanghai

Tel: 86-21-5407-5533 Fax: 86-21-5407-5066

China - Shenyang

Tel: 86-24-2334-2829 Fax: 86-24-2334-2393

China - Shenzhen

Tel: 86-755-8203-2660 Fax: 86-755-8203-1760

China - Wuhan

Tel: 86-27-5980-5300 Fax: 86-27-5980-5118

China - Xian

Tel: 86-29-8833-7252 Fax: 86-29-8833-7256

China - Xiamen

Tel: 86-592-2388138 Fax: 86-592-2388130

China - Zhuhai

Tel: 86-756-3210040 Fax: 86-756-3210049

ASIA/PACIFIC

India - Bangalore

Tel: 91-80-3090-4444 Fax: 91-80-3090-4123

India - New Delhi

Tel: 91-11-4160-8631 Fax: 91-11-4160-8632

India - Pune

Tel: 91-20-2566-1512 Fax: 91-20-2566-1513

Japan - Yokohama

Tel: 81-45-471- 6166 Fax: 81-45-471-6122

Korea - Daegu

Tel: 82-53-744-4301 Fax: 82-53-744-4302

Korea - Seoul

Tel: 82-2-554-7200 Fax: 82-2-558-5932 or 82-2-558-5934

Malaysia - Kuala Lumpur

Tel: 60-3-6201-9857 Fax: 60-3-6201-9859

Malaysia - Penang

Tel: 60-4-227-8870 Fax: 60-4-227-4068

Philippines - Manila

Tel: 63-2-634-9065 Fax: 63-2-634-9069

Singapore

Tel: 65-6334-8870 Fax: 65-6334-8850

Taiwan - Hsin Chu

Tel: 886-3-6578-300 Fax: 886-3-6578-370

Taiwan - Kaohsiung

Tel: 886-7-213-7830 Fax: 886-7-330-9305

Taiwan - Taipei

Tel: 886-2-2500-6610 Fax: 886-2-2508-0102

Thailand - Bangkok

Tel: 66-2-694-1351 Fax: 66-2-694-1350

EUROPE

Austria - Wels

Tel: 43-7242-2244-39 Fax: 43-7242-2244-393

Denmark - Copenhagen

Tel: 45-4450-2828 Fax: 45-4485-2829

France - Paris

Tel: 33-1-69-53-63-20 Fax: 33-1-69-30-90-79

Germany - Munich

Tel: 49-89-627-144-0 Fax: 49-89-627-144-44

Italy - Milan

Tel: 39-0331-742611 Fax: 39-0331-466781

Netherlands - Drunen

Tel: 31-416-690399 Fax: 31-416-690340

Spain - Madrid Tel: 34-91-708-08-90

Fax: 34-91-708-08-91 **UK - Wokingham**

Tel: 44-118-921-5869 Fax: 44-118-921-5820

05/02/11



Компания «Океан Электроники» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

Наши преимущества:

- Поставка оригинальных импортных электронных компонентов напрямую с производств Америки, Европы и Азии, а так же с крупнейших складов мира;
- Широкая линейка поставок активных и пассивных импортных электронных компонентов (более 30 млн. наименований);
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Помощь Конструкторского Отдела и консультации квалифицированных инженеров;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Поставка электронных компонентов под контролем ВП;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001;
- При необходимости вся продукция военного и аэрокосмического назначения проходит испытания и сертификацию в лаборатории (по согласованию с заказчиком);
- Поставка специализированных компонентов военного и аэрокосмического уровня качества (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Actel, Aeroflex, Peregrine, VPT, Syfer, Eurofarad, Texas Instruments, MS Kennedy, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Компания «Океан Электроники» является официальным дистрибьютором и эксклюзивным представителем в России одного из крупнейших производителей разъемов военного и аэрокосмического назначения «JONHON», а так же официальным дистрибьютором и эксклюзивным представителем в России производителя высокотехнологичных и надежных решений для передачи СВЧ сигналов «FORSTAR».



«JONHON» (основан в 1970 г.)

Разъемы специального, военного и аэрокосмического назначения:

(Применяются в военной, авиационной, аэрокосмической, морской, железнодорожной, горно- и нефтедобывающей отраслях промышленности)

«**FORSTAR**» (основан в 1998 г.)

ВЧ соединители, коаксиальные кабели, кабельные сборки и микроволновые компоненты:

(Применяются в телекоммуникациях гражданского и специального назначения, в средствах связи, РЛС, а так же военной, авиационной и аэрокосмической отраслях промышленности).



Телефон: 8 (812) 309-75-97 (многоканальный)

Факс: 8 (812) 320-03-32

Электронная почта: ocean@oceanchips.ru

Web: http://oceanchips.ru/

Адрес: 198099, г. Санкт-Петербург, ул. Калинина, д. 2, корп. 4, лит. А